

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : YEH et al. Confirmation No: 8986  
Appl. No. : 10/075,293  
Filed : February 15, 2002  
Title : METHOD OF REDUCING THICK FILM STRESS OF  
SPIN-ON DIELECTRIC AND THE RESULTING SANDWICH  
DIELECTRIC STRUCTURE

TC/A.U. : 2814  
Examiner : H. Trinh

Docket No.: : YEHC3010/REF  
Customer No: : 23364

I HEREBY CERTIFY THAT THIS  
PAPER IS BEING FACSIMILE  
TRANSMITTED TO THE U.S. P.T.O.  
ON THE DATE SHOWN BELOW.

(PRINT) KATHLEEN DEPASSE  
(SIGN) Kathleen Depasse  
(DATE) Feb 26, 2004

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in further response to the Final Rejection of September 8, 2003. A timely filed Notice of Appeal with a one month extension of time was filed on January 8, 2004 as full response to the Final Rejection. The appeal brief is now due on March 8, 2004. The present amendment is being filed in an effort to place the application in condition for allowance and to avoid the necessity to proceed with the preparation and filing of an appeal brief.

Please amend the above-identified application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.